L Number	Hits	Search Text	DB	Time stamp
7	2328	wafer and (adhesi$4 and barrier) adj (layer or film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:00
8	14	(wafer and (adhesi$4 and barrier) adj (layer or film)) and photo near (lithograph$6 and resist) and etch$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:00
9	11	((wafer and (adhesi$4 and barrier) adj (layer or film)) and photo near (lithograph$6 and resist) and etch$4) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 14:59
10	1	("20020064935").PN.	USPAT; US-PGPUB	2004/08/26 14:58
11	1	("20030099767").PN.	USPAT; US-PGPUB	2004/08/26 14:59
12	32288	solder near (bump or ball or sphere or block or preform)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 14:59
13	1228	(solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:00
14	288	((solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)) and (solder or bump or ball or sphere or block or preform) near (stack$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:00
15	14	(((solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)) and (solder or bump or ball or sphere or block or preform) near (stack$4)) and wafer and (adhesi$4 and barrier) adj (layer or film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:01
16	0	((((solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)) and (solder or bump or ball or sphere or block or preform) near (stack$4)) and wafer and (adhesi$4 and barrier) adj (layer or film)) and photo near (lithograph$6 and resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:01
17	30	((solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)) and wafer and (adhesi$4 and barrier) adj (layer or film)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:01
18	0	(((solder near (bump or ball or sphere or block or preform)) and (solder or bump or ball or sphere or block or preform) near (column or stack$4 or tower)) and wafer and (adhesi$4 and barrier) adj (layer or film)) and photo near (lithograph$6 and resist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/26 15:01